

**POLISHING PAD, MANUFACTURING METHOD THEREOF, METHOD FOR
MANUFACTURING SEMICONDUCTOR DEVICE USING SAME**

ABSTRACT

5 The present disclosure relates to a polishing pad, a method for manufacturing the
polishing pad, and a method for manufacturing a semiconductor device using the polishing
pad, and the present disclosure can prevent an error in detecting the end point due to the
window in the polishing pad by minimizing the effect on transmittance according to the
surface roughness of the window in the polishing pad in the polishing process, and allows
10 the fluidity and loading rate of the polishing slurry in the polishing process to be
implemented at similar levels by maintaining the surface roughness difference between the
polishing layer and the window in the polishing pad within the predetermined range,
thereby enabling the problem of deterioration of polishing performance due to the surface
difference between the polishing layer and the window to be prevented.

15 Further, a method for manufacturing a semiconductor device to which a polishing
pad is applied may be provided.

[FIG 2]